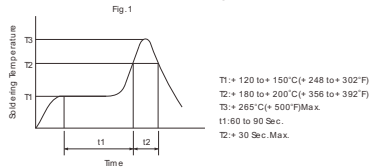




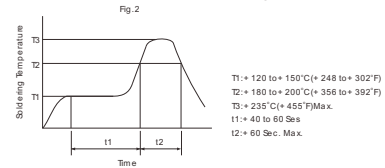
## SOLDERING and MOUNTING RECOMMENDATIONS

### 1. Conditions for Terminal Soldering by reflow soldering method

#### a. In case of Infrared Soldering



#### b. In case of Vapor Phase Soldering



### 2. Usage of Stand-Off A & B Bin Base Area

The Stand-Offs shown in the Fig. 3 are designed to Anchor Relays temporarily to PC Board with glue before Terminal Soldering.

